

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**In the Specification:**

The paragraph starting at page 5, line 29 has been amended as follows:

With reference back to Figure 2A, a wafer carrier, which is indicated generally by the reference number 50, is attached to the elevator plate 26. Preferably, the wafer carrier 50 is sized and dimensioned to simultaneously support at least two wafers 37. Therefore, in the preferred embodiment, the wafer carrier 50 consists of a pair of supports or prongs 52a, 52b that extend generally upward from the lining 44. The prongs 52a, 52b are preferably secured to the elevator plate 26 by fasteners 54 that extend through the elevator plate 26 and the lining 44. Each prong 52a, 52b includes two arms 56, 57 that extend towards the center of the elevator plate [load lock chamber] 26. Together, the first set of arms 56 form a first shelf 56 for a wafer and the second set of arms 57 form a second shelf 57 for a wafer. Thus, as shown in Figure 2A, two wafers 37 can simultaneously rest on the first and second shelves 56, 57 of the wafer carrier 50.

**In the Claims:**

Claims 7, 63 and 64 have been amended as follows:

7. (TWICE AMENDED) A load lock that defines at least partially a first chamber and an auxiliary chamber, said load lock comprising:

a first port and a second port, said first and second ports for moving a wafer into and out of said load lock;

an elevator plate including a wafer carrier that is adapted for receiving a plurality of wafers; and

said wafer carrier being moveable between a first position where said wafer carrier is in said first chamber and a second position where said wafer carrier is in said auxiliary chamber and said elevator plate substantially seals said auxiliary chamber from said first chamber, wherein said first and second ports open into said first chamber when said elevator plate is in said second position.

63. (AMENDED) A system for processing substrates, comprising

a load lock chamber including a lower portion having a first inner width and an upper portion having a narrower second inner width, the chamber including a first port and a second port, each of the ports sized to pass substrates therethrough, the load lock chamber further comprising a moveable platform configured to support at least one substrate thereon and sized to have a width less than the first inner width and greater than the second inner width to enable selectively sealing the upper portion with the at least one substrate supported thereon;

a substrate handling chamber selectively communicating with the load lock chamber through the first port; and

at least one process chamber selectively communicating with the substrate handling chamber, wherein the upper portion includes treatment gas injectors and [The system of Claim 62,] wherein the treatment gas injectors communicate with a source of HF vapor.

64. (AMENDED) A system for processing substrates, comprising

a load lock chamber including a lower portion having a first inner width and an upper portion having a narrower second inner width, the chamber including a first port and a second port, each of the ports sized to pass substrates therethrough, the load lock chamber further comprising a moveable platform configured to support at least one substrate thereon and sized to have a width less than the first inner width and greater than the second inner width to enable selectively sealing the upper portion with the at least one substrate supported thereon;

a substrate handling chamber selectively communicating with the load lock chamber through the first port; and

at least one process chamber selectively communicating with the substrate handling chamber, wherein the upper portion includes treatment gas injectors and [The system of Claim 62,] wherein the treatment gas injectors communicate with an oxidant source.